momentum_cmos028FDSOI_6U1x_2T8x_LB
Momentum Technology Kit

Version 4.0
(Production release)

Release Notes

July 2018

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Product name: *momentum_cmos028FDSOI_6U1x_2T8x_LB 4.0*

This version 4.0 of the Momentum module dedicated to cmos028FDSOI technology with 8 metal layers is aligned on DK_cmos28FDSOI_RF_mmW_6U1x_2T8x_LB version 1.1. This module is compatible with Momentum on RFDE in **ADS 2017_update0.2 (and later versions)**.

Additional feature:

- Temperature coefficients are provided in Momentum technology files in order to emulate temperature dependency of sheet resistance.

This module has been validated with the following configuration:

ads 2017_update0.2
ic 06.17.720
DK_cmos28FDSOI_RF_mmW_6U1x_2T8x_LB 1.1-DEV-32

Module content:

- Five Momentum technology files describing the cmos028 technology for nominal and 2 additional corner process conditions (NOMINAL, RCMIN and RCMAX). 2 additional techfiles are provided to emulate NOMINAL corner in PWELL or VVLARGE configuration. Each of them includes temperature coefficient (TC) values for temperature dependency assessment of metal layers sheet resistance.
- Pre-computed substrate database corresponding to the technology files and containing the Green functions for capacitance extraction.
- Via merging procedures through Momentum engine (internal preprocessor) or using skill procedures (layout processing)
- Derived layer to manage Conformal Alucap modeling and Via Contact management.
- A setup file for loading automatically the correct settings related to technology file (expansion UP/DOWN per layer, 2D or 3D current, recommended options, etc...).
- Documentation.